

SQS24LF w/Green mold compound summary material content, BI Technologies Corp.

8/27/2007

No content here is banned per E.U. Ro.S. Prepared by Eric Arnold (714) 447-2565

Average mass of SQS24LF Thin Film network is 0.120 grams each. Scientific notation is used for all component masses.

Material name	also known as	CAS #	Weight per unit (grams)	Special classification
Ag	silver	7440-22-4	1.94E-03	
Au	gold	7440-57-5	5.55E-05	
BCB	dvs-BCB, divinylsiloxane-bis-benzocyclobutene	124221-30-3	5.16E-06	
carbon black	lamp black, acetylene black	1333-86-4	3.32E-04	
Cu	copper	7440-50-8	4.06E-02	
epoxy curing agent		trade secret	2.10E-05	
epoxy resin		trade secret	1.89E-04	
epoxy resin, cresol novolac		29690-82-2	1.33E-03	
Fe	iron	7439-89-6	9.79E-04	
NiCrOx	nichrome	combination of 7440-02-0, 7440-47-3, & 1308-38-9	1.61E-07	
P	phosphorous, red or amorphous	7723-14-0	1.25E-05	
Si	silicon	7440-21-3	7.99E-03	
SiO2, amorphous	silicon dioxide, silica	7631-86-9	2.52E-05	
SiO2, fused silica	silica glass	60676-86-0	5.81E-02	
Sn	tin	7440-31-5	1.75E-03	
Ti	titanium	7440-32-6	2.30E-08	
trade secret		n/a	6.68E-03	Non-hazardous and not regulated
W	tungsten or wolfram	7440-33-7	2.07E-07	
Zn	zinc	7440-66-6	5.00E-05	
Sum of all components			0.120	